

L Number	Hits	Search Text	DB	Time stamp
1	9	4778326.pn. 5590787.pn. 4990051.pn. 4850780.pn. 4915565.pn. 4759675.pn. 4285433.pn. 4607744.pn. 6202292.pn.	USPAT; US-PGPUB	2004/08/05 09:01
2	5202	438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584.ccls.	USPAT; US-PGPUB	2004/08/05 09:03
3	39	(438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584.ccls.) and (dbg (dic\$6 near2 grind\$6))	USPAT; US-PGPUB	2004/08/05 09:36
4	166	(dbg (dic\$6 near2 grind\$6))	EPO; JPO; DERWENT; IBM_TDB	2004/08/05 09:06
6	28	((wafer dic\$6 protective) adj tape) same (release adj tape)	USPAT; US-PGPUB	2004/08/05 13:03
7	3	((wafer dic\$6 protective) adj tape) and (release adj tape)	EPO; JPO; DERWENT; IBM_TDB	2004/08/05 09:29
8	2	jp-2003209073-\$.did.	EPO; JPO; DERWENT; IBM_TDB	2004/08/05 09:30
9	39	(438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584.ccls.) and (dbg (dic\$6 near2 grind\$6))	USPAT; US-PGPUB	2004/08/05 09:36
10	5	6297131.URPN.	USPAT	2004/08/05 11:30
11	2	("5960260"   "6048749").PN.	USPAT	2004/08/05 11:41
5	108	((dbg (dic\$6 near2 grind\$6))) and (semiconductor wafer package chip ic integrated die dice silicon tape)	EPO; JPO; DERWENT; IBM_TDB	2004/08/05 12:04
12	220	(438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584.ccls.) and ((wafer dic\$6 protect\$6 releas\$6) adj tape)	USPAT; US-PGPUB	2004/08/05 14:22
13	120	((438/108.ccls. 438/113.ccls. 438/114.ccls. 438/459.ccls. 438/461.ccls. 438/464.ccls. 438/465.ccls. 438/977.ccls. 29/740.ccls. 29/743.ccls. 156/584.ccls.) and ((wafer dic\$6 protect\$6 releas\$6) adj tape)) and (((die chip) adj pad) leadframe (lead adj frame) ((uv ultraviolet) with adhe\$8))	USPAT; US-PGPUB	2004/08/05 14:23
14	38	5480842.URPN.	USPAT	2004/08/05 14:04
15	12	("3631307"   "3702464"   "4266334"   "4417413"   "4862490"   "4889980"   "5127984"   "5250600"   "5255430"   "5261999"   "5311396"   "5399907").PN.	USPAT	2004/08/05 14:20
16	6	((wafer dic\$6 protect\$6 releas\$6) adj tape) same (((die chip) adj pad) with (leadframe (lead adj frame) (((package wiring) adj substrate) carrier) with (solder adj ball))))	USPAT; US-PGPUB	2004/08/05 14:46
17	0	((wafer dic\$6 protect\$6 releas\$6) adj tape) same ((die chip) adj pad) same (leadframe (lead adj frame)) same (((package wiring) adj substrate) carrier module) with (solder adj ball))	USPAT; US-PGPUB	2004/08/05 14:49
18	2	((die chip) adj pad) same (leadframe (lead adj frame)) same (((package wiring) adj substrate) carrier module) with (solder adj ball))	USPAT; US-PGPUB	2004/08/05 14:49
-	0	kr-199969593-\$.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/04 16:59
-	1	1998kr-0003970.ap,prai.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/27 09:05

-	2023	(semiconductor wafer package chip ic integrated die dice silicon) with tape with apparatus	USPAT; US-PGPUB	2004/08/05 09:07
-	1808	(semiconductor wafer chip ic integrated die dice silicon) with tape with apparatus	USPAT; US-PGPUB	2004/08/04 17:02